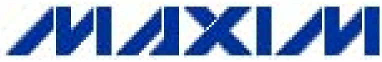

RELIABILITY REPORT

FOR

MAX398ESE+

PLASTIC ENCAPSULATED DEVICES

August 14, 2012

MAXIM INTEGRATED PRODUCTS

160 Rio Robles

San Jose, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

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Conclusion

The MAX398ESE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX398/MAX399 precision, monolithic, CMOS analog multiplexers (muxes) offer low on-resistance (less than 100), which is matched to within 6 between channels and remains flat over the specified analog signal range (11 max). They also offer low leakage over temperature (NO off-leakage current less than 2.5nA at +85°C) and fast switching speeds (transition time less than 250ns). The MAX398 is an 8-channel device, and the MAX399 is a dual 4-channel device. The MAX398/MAX399 are fabricated with Maxim's low-voltage silicon-gate process. Design improvements yield extremely low charge injection (less than 5pC) and guarantee electrostatic discharge protection (ESD) greater than 2000V. These muxes operate with a single +3V to +15V supply or bipolar ±3V to ±8V supplies, while retaining CMOS-logic input compatibility and fast switching. CMOS inputs provide reduced input loading. The MAX398/MAX399 are pin compatible with the industry-standard DG408, DG409, DG508A, and DG509A.

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II. Manufacturing Information

A. Description/Function:	Precision, 8-Channel/Dual 4-Channel, Low-Voltage, CMOS Analog Multiplexers
B. Process:	SG5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	150 mil 16L SOIC
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0301-0659 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	115°C/W
K. Single Layer Theta Jc:	32°C/W
L. Multi Layer Theta Ja:	75°C/W
M. Multi Layer Theta Jc:	24°C/W

IV. Die Information

A. Dimensions:	80 X 102 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 400 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 2.7 \times 10^{-9}$

λ = 2.7 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the SG5 Process results in a FIT Rate of 0.12 @ 25C and 2.04 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot NDTADA015C D/C 0029, Latch-up lot NDTAEA038A D/C 0427)

The AG66 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

MAX398ESE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)					
	Ta = 135°C	DC Parameters	80	0	NDTADA015B, D/C 0029
	Biased	& functionality	80	0	NDTBEA023D, D/C 0106
	Time = 192 hrs.		80	0	XDTABB004B, D/C N/A
			80	0	XDTAAQ001A, D/C 9431
			80	0	XDTBBY001A, D/C 9431

Note 1: Life Test Data may represent plastic DIP qualification lots.

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